



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

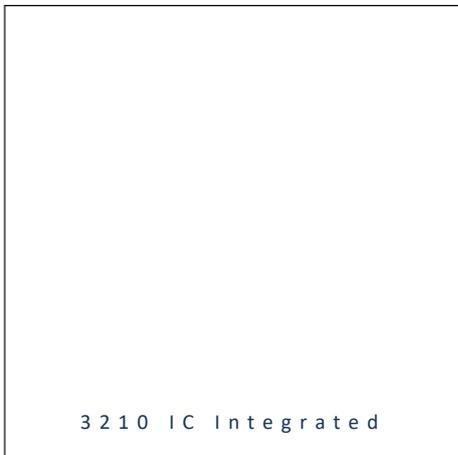


- ▶ PCB Side View SMD with IC
- ▶ 3210ICSV 0.8t Series
- ▶ Red/Green/Blue

NOM67S09ICSV



Release Date: 11 December 2024 Version: A1.4



3 2 1 0 I C I n t e g r a t e d

3210 IC-Integrated

RoHS
Compliant



FEATURES:

- **Package:** PCB Side View Package with Integrated IC
- **Forward Current:** 5mA
- **IC Power Supply Voltage:** +3.8~+5.5V
- **Luminous Intensity (typ.):** Mixed White 380mcd
- **Colour:** Red/Green/Blue with White Diffused Lens
- **Dominant Wavelength (typ.):** 622/527/467nm
- **Viewing angle:** 120°
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+105°C
- **IC Feature:** Serial data transmission signal by single wire. RGB and driver chip are integrated in a package, to form a complete control of pixel point with constant current. One pixel contains R, G, and B colour that each can achieve 256 level brightness grayscales, which forms 16,777,216 combination colours. The signal communication frequency is 800 KHz.
- **Soldering methods:** Reflow soldering
- **MSL Level:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with max.4000pcs/reel, ø180mm (7")

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- Decoration Lighting
- Full Colour LED Strip
- Gaming Device

CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	5	mA
IC Power Supply Voltage	V _{DD}	+3.8~+5.5	V
R/G/B Output Port Withstand Voltage	V _{ds}	9	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+105	°C
Soldering Temperature	T _{SD}	260 for 10s max.	°C
Electrostatic Discharge acc. To ANSI/ESDA/JEDEC JS-001	ESD	2	kV

Electrical & Optical Characteristics (T_a=25°C; V_{DD}=5V)

Parameter	Symbol	Values			Unit	Test Condition	
		Min.	Typ.	Max.			
Luminous Intensity	R	I _v	63	130	200	mcd	I _F =5mA
	G		125	230	400		
	B		13	34	63		
Mixed White	W	I _v	250	380	800	mcd	I _F =3*5mA
Dominant Wavelength	R	λ _D	615	---	630	nm	I _F =5mA
	G		520	---	535		
	B		460	---	475		
Colour Coordinate	X	---	---	0.3041	---	---	I _F =3*5mA
	Y		---	0.2814	---		
Viewing Angle	2θ _{1/2}	---	120	---	deg	I _F =3*5mA	

1. Tolerance of Measure: Luminous Intensity: ±10% mcd, Dominant Wavelength: ±1.0 nm, Color Coordinate: ±0.005

Electrical & Optical Characteristics ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Quiescent Current	I_{DD}	---	0.45	---	mA	$V_{DD}=4.5\text{V}$ $I_{OUT}=\text{"OFF"}$
Input Voltage Level	V_{IH}	3.1	---	---	V	D_{IN} , Input High Level V
	V_{IL}	---	---	1.5	V	D_{IN} , Input Low Level V

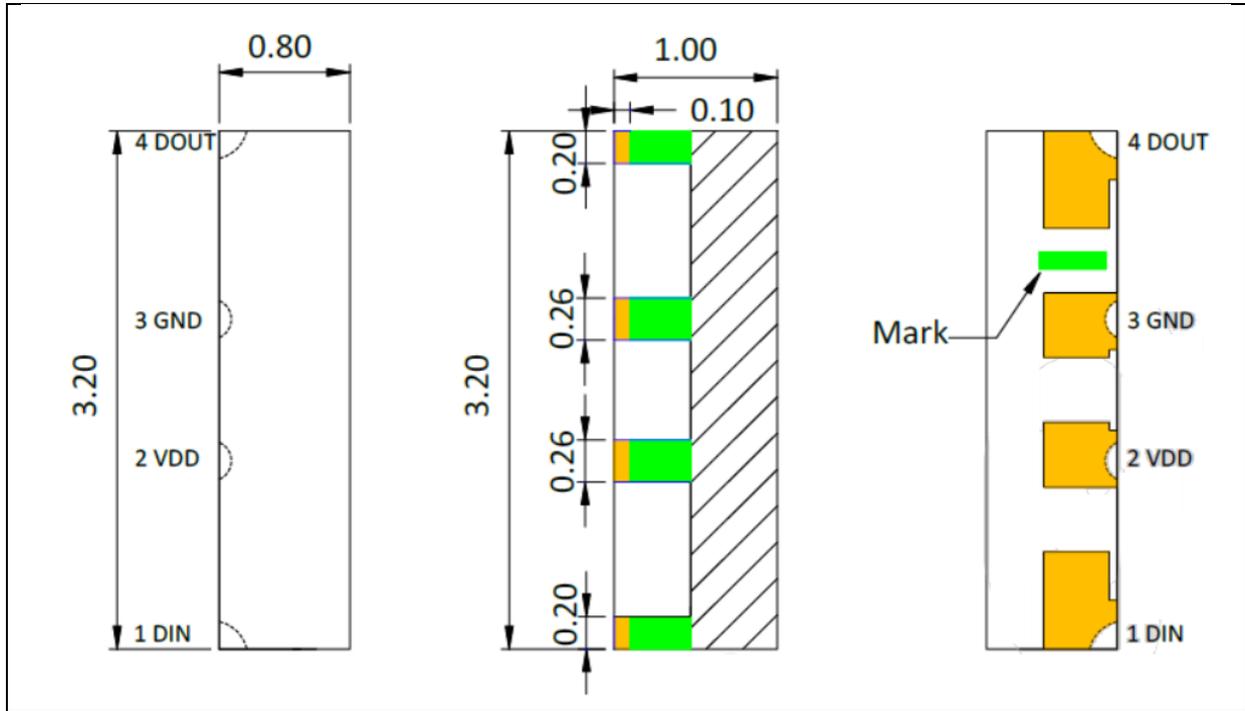
 Switching Characteristics ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Rate of Data Signal	F_{DIN}	---	800	---	kHz	---
Transfer Time	T_{PLH}	---	---	80	ns	$D_{IN} \rightarrow D_{OUT}$ D_{OUT} Port to GND $CL=30\text{pF}$
	T_{PHL}	---	---	80	ns	
Conversion Time of I_{OUT} R/G/B	T_r	---	500	---	ns	I_{OUT} R/G/B=5mA $RL=200\Omega$ $CL=30\text{pF}$
	T_f	---	500	---	ns	



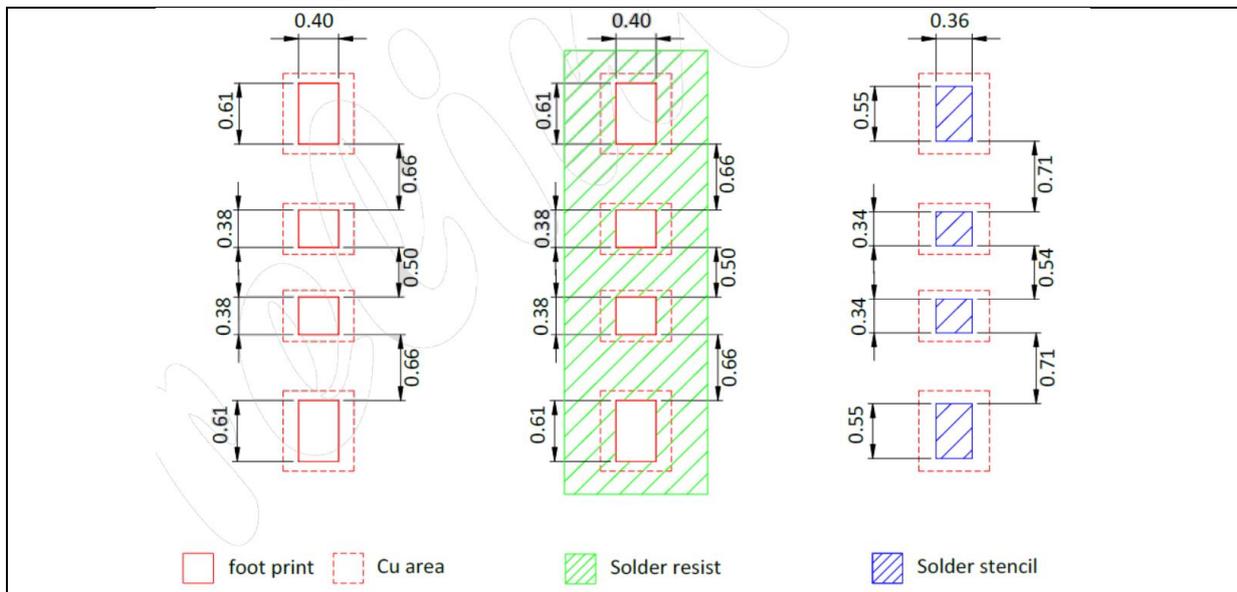
OUTLINE DIMENSION:

Package Dimension:



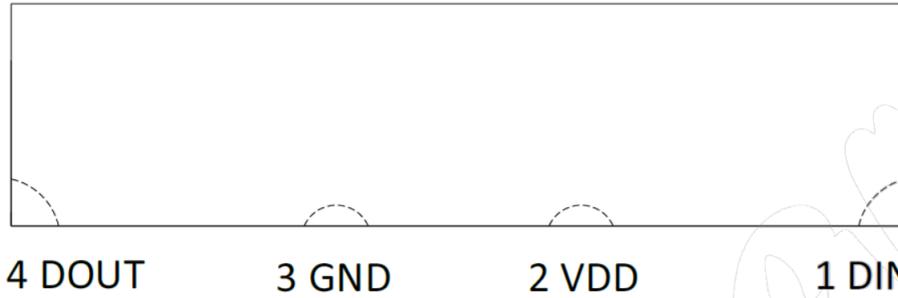
1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.2\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.1\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

PIN CONFIGURATION:

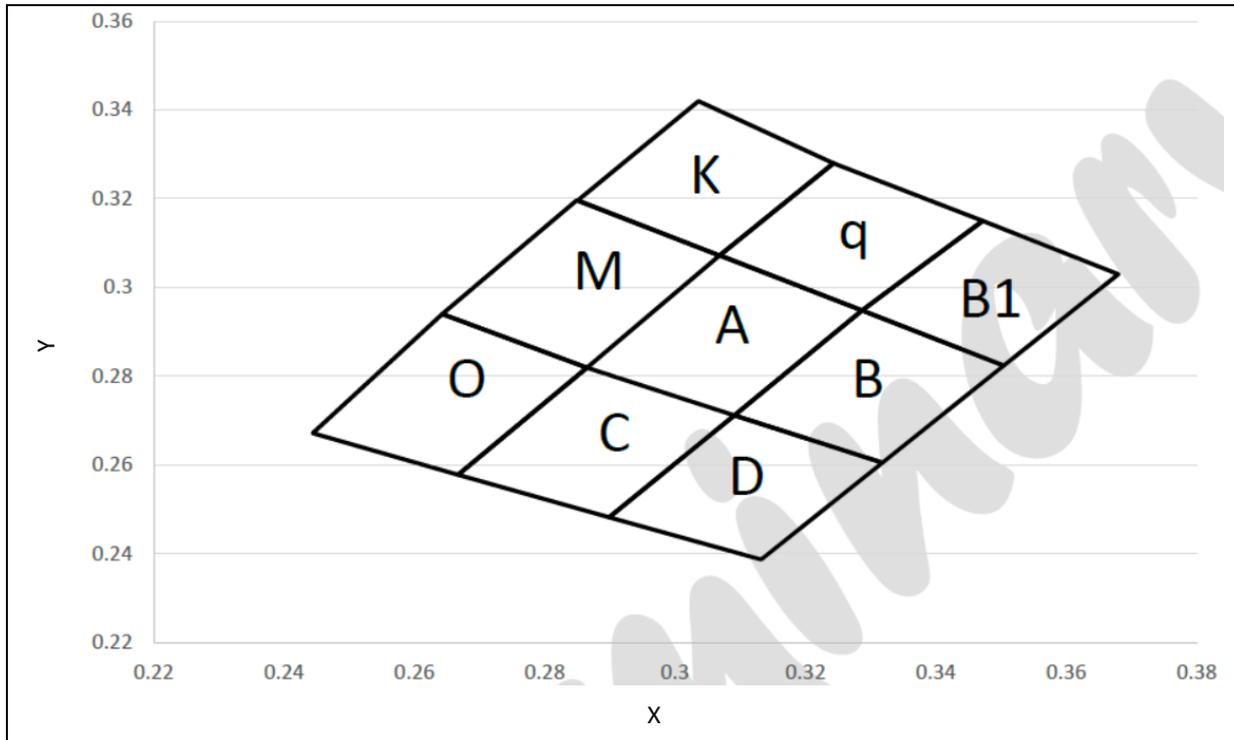


No.	Symbol	Function Description
1	DIN	Control Data Signal Input
2	VDD	Power Supply LED
3	GND	Ground
4	DOUT	Control Data Signal Output

BINNING GROUPS:

Luminous Intensity Classifications (White) ($I_F=3*5\text{mA}$, $V_{DD}=5\text{V}$):

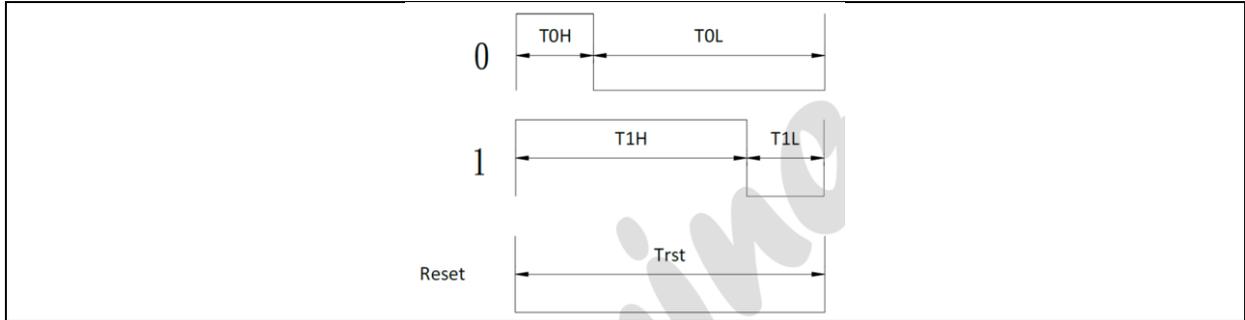
Code	Min.	Max.	Unit
15	200	250	mcd
16	250	320	
17	320	400	
18	400	500	
19	500	630	

CIE CHROMATICITY DIAGRAM:

 Chromaticity Coordinates Classifications ($I_F=3*5mA$; $V_{DD}=5V$):

	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
K	0.2851	0.3196	0.3036	0.3420	0.3243	0.3280	0.3068	0.3072
q	0.3068	0.3072	0.3243	0.3280	0.3472	0.3150	0.3287	0.2948
B1	0.3472	0.3150	0.3680	0.3030	0.3504	0.2824	0.3287	0.2948
M	0.2643	0.2940	0.2849	0.3196	0.3068	0.3072	0.2865	0.2819
A	0.3070	0.3072	0.3287	0.2948	0.3091	0.2712	0.2865	0.2819
B	0.3504	0.2824	0.3287	0.2948	0.3091	0.2712	0.3318	0.2605
O	0.2444	0.2672	0.2643	0.2940	0.2865	0.2819	0.2667	0.2578
C	0.2865	0.2819	0.3091	0.2712	0.2899	0.2482	0.2667	0.2578
D	0.3091	0.2712	0.3318	0.2605	0.3132	0.2387	0.2899	0.2482

DATA TRANSFER TIME:

1. Timing Wave Form



2. Data Transfer Time:

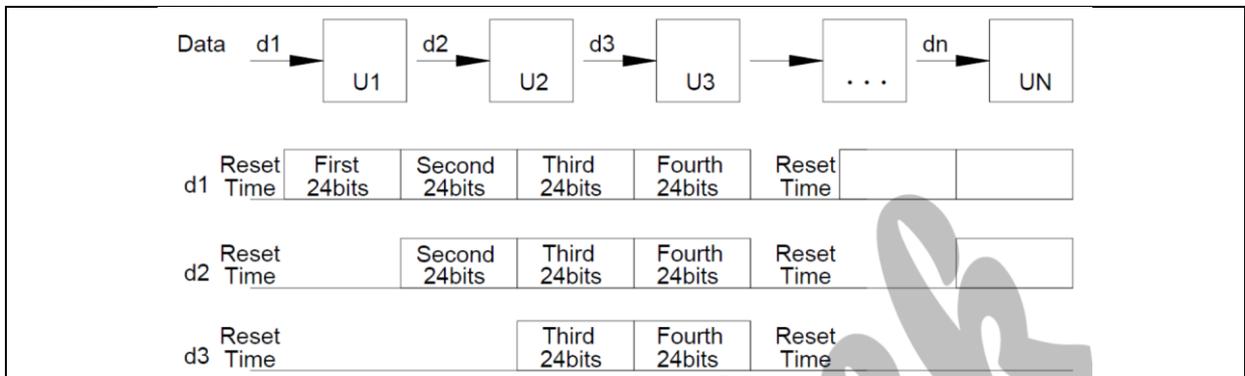
Item	Description	Typical	Allowance
T _{0H}	0 code, high voltage time	0.3μs	±0.05μs
T _{0L}	0 code, low voltage time	0.9μs	±0.05μs
T _{1H}	1 code, high voltage time	0.9μs	±0.05μs
T _{1L}	1 code, low voltage time	0.3μs	±0.05μs
T _{rst}	Reset Time, low voltage time	>200μs	---

3. Composition of 24 Bits Data

G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4	R3	R2	R1	R0	B7	B6	B5	B4	B3	B2	B1	B0
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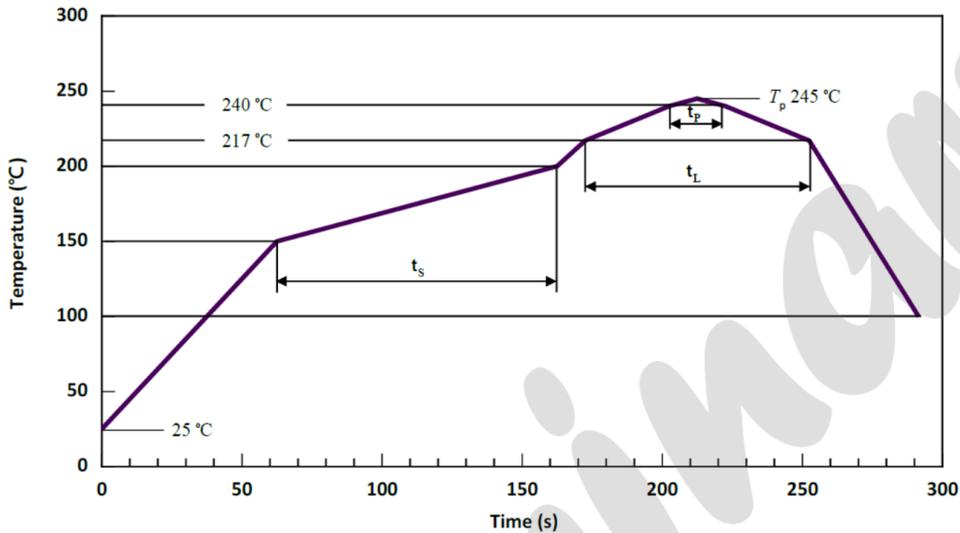
The single wire data transfer protocol supports 24-bits data for each LED's RGB display data refresh. ICLED receives 24-bits data and passes the remaining data to the next ICLED. The 24-bits data consist of green, red and blue data, each with 8-bits width, and are transferred with MSB first.

4. Data Transmission Method



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:



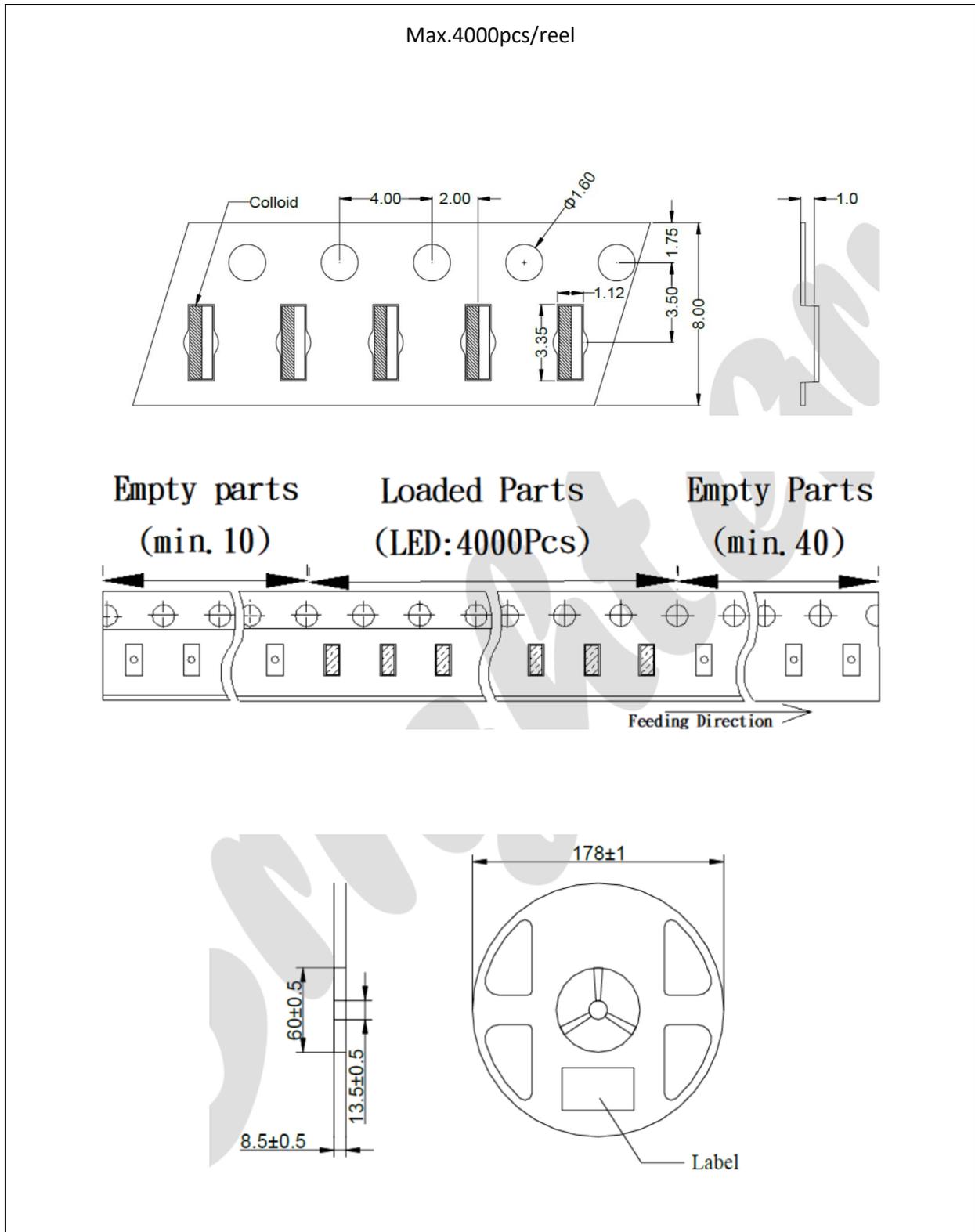
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up Rate to Preheat 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up Rate to Peak T_{Smax} to T_p			2	3	K/s
Liquids Temperature	T_L		217		°C
Time Above Liquids Temperature	t_L		80	100	s
Peak Temperature	T_p		245	260	°C
Time Within 5 °C of the Specified Peak Temperature $T_p - 5$ K	T_p			10	s
Ramp-Down Rate T_p to 100 °C			3	4	K/s
Time 25 °C to T_p				480	s

Note:

1. We recommend the reflow temperature 240°C ($\pm 5^\circ\text{C}$). The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 1 week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking.

Over-Current Proof:

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burn-out will happen.

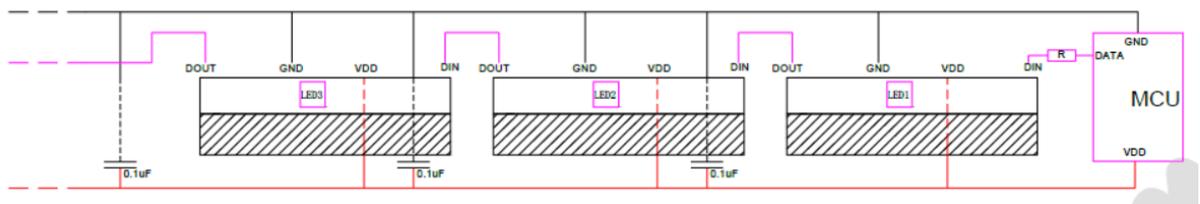
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 6hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Typical Application Circuit:



When the first LED is connected to the MCU, a resistance R is needed in series between its signal input line and the MCU. The size of R depends on the number of cascade beads. The more cascades, the smaller resistance R is used. It is generally recommended that the value be between 100-1K. Usually the recommended value is around 300 R. In order to make the LEDs work more stably, a parallel capacitor is needed between VDD and GND of each LED.

In order to avoid harmful effects in use, please try to add resistance and capacitance when using. If capacitors and resistors are not added, the number of LEDs on the lamp should be minimized, but this way still does not exclude the risk of problems.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	24/04/2022	Datasheet set-up.
A1.1	30/08/2024	Add bin table.
A1.2	19/09/2024	Add polarity on drawing.
A1.3	23/09/2024	Revise pin table.
A1.4	11/12/2024	Revised package dimensions.